

280  
604

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23  
FIGS

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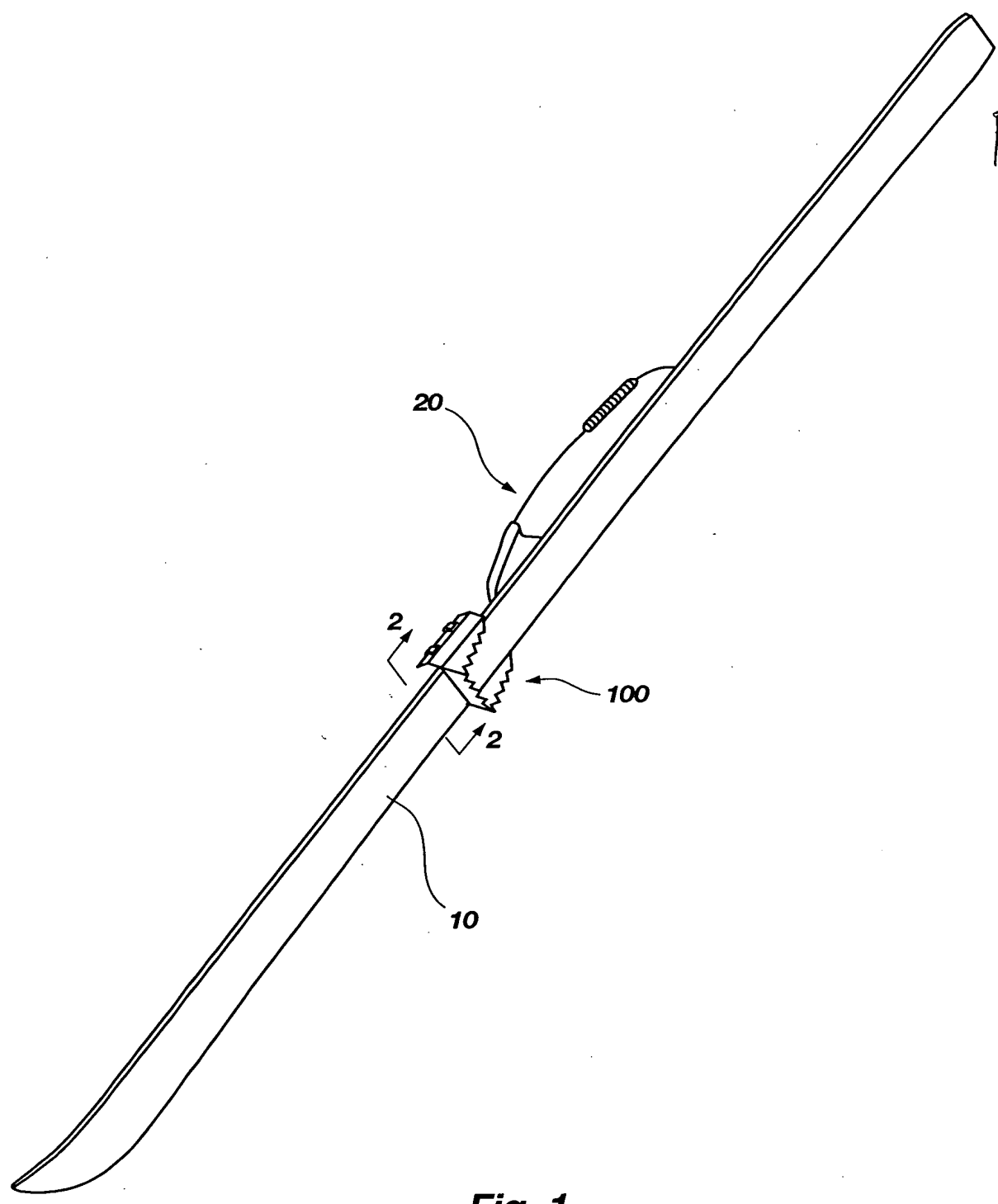


Fig. 1

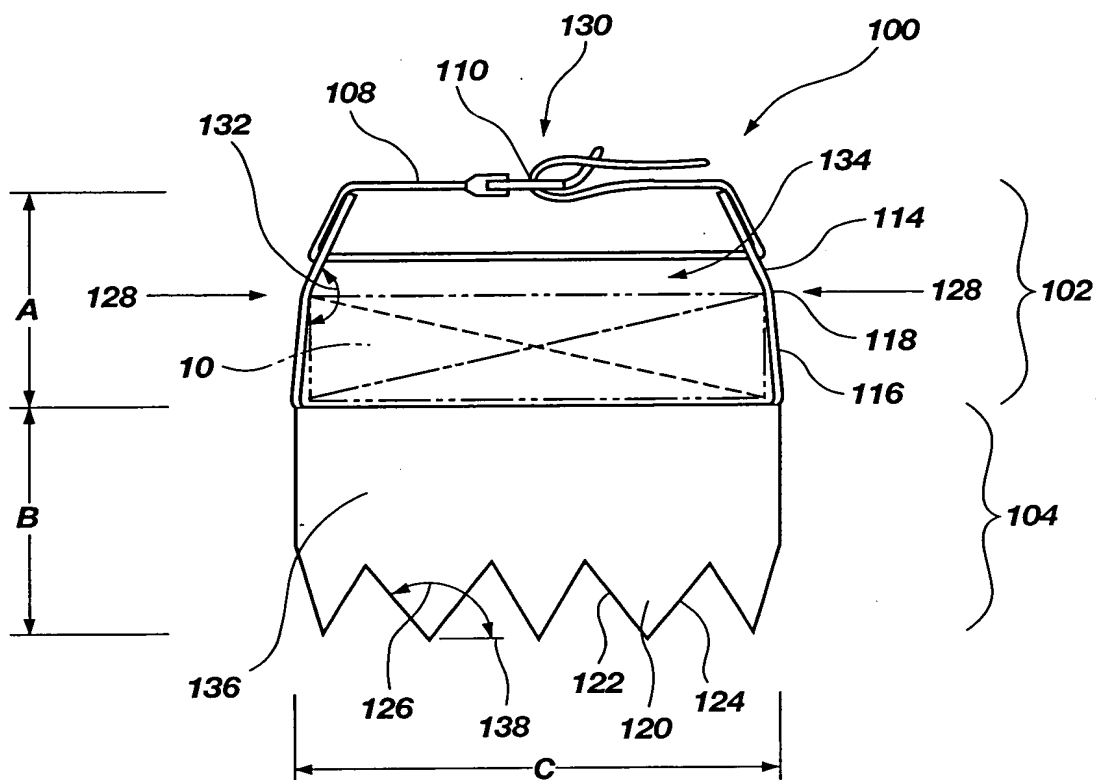


Fig. 2

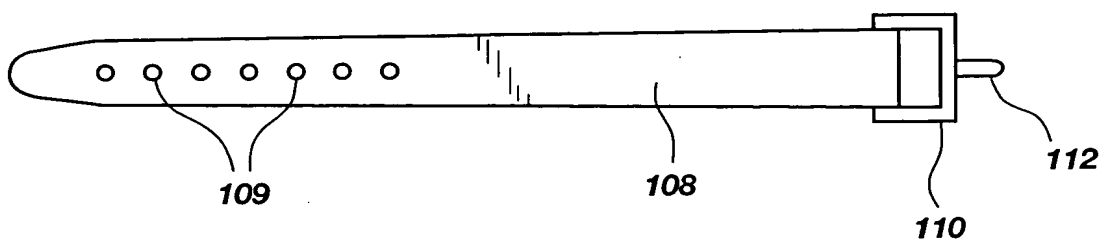
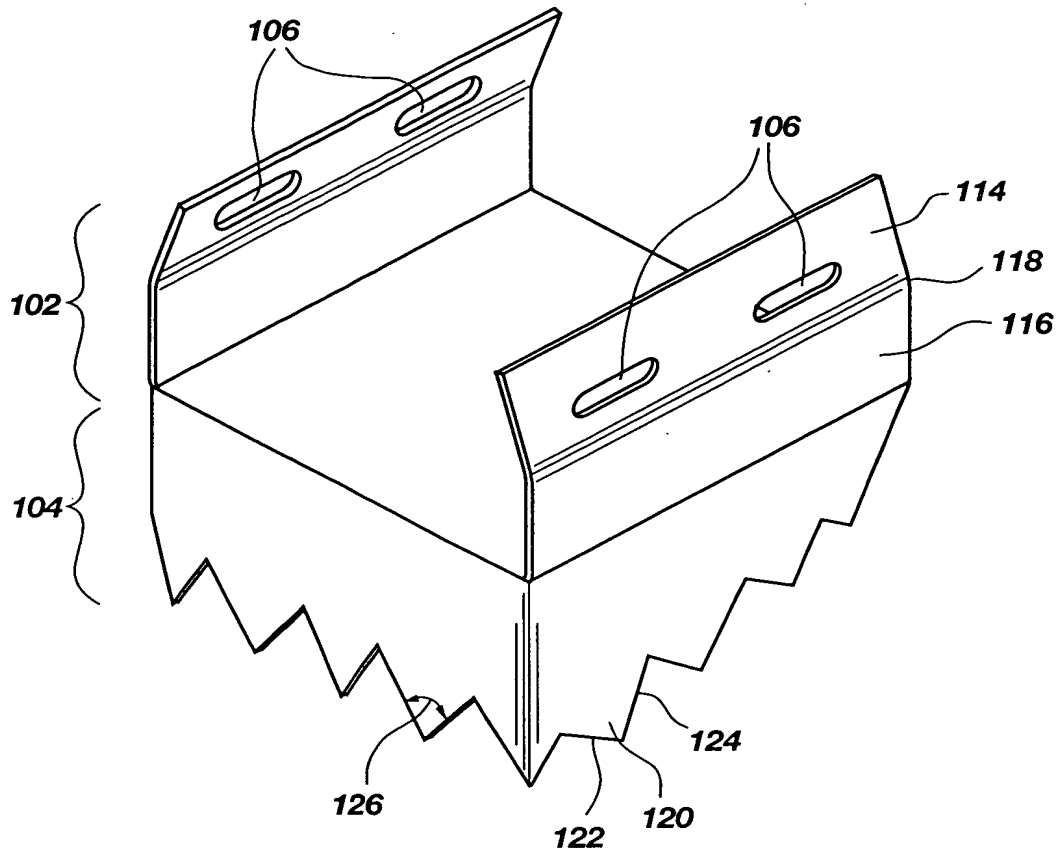
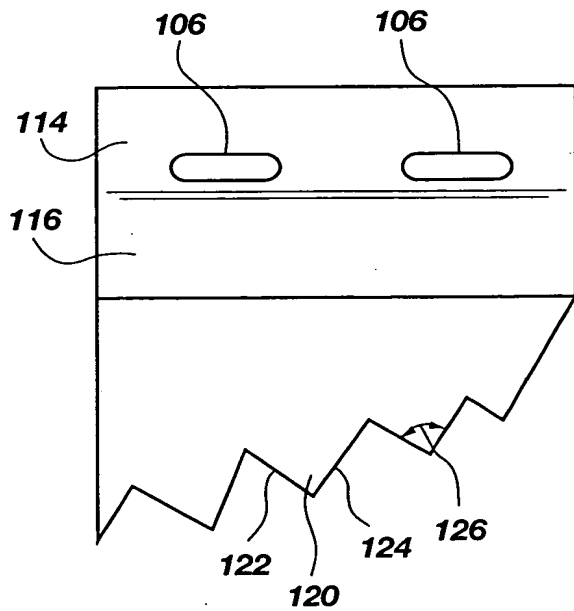


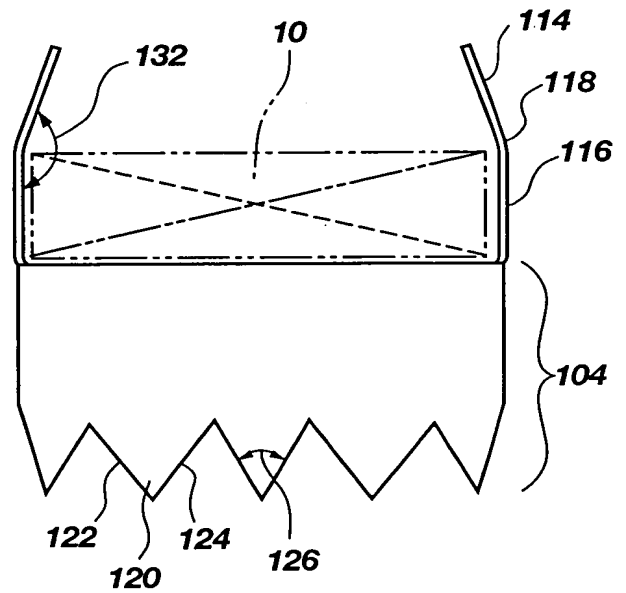
Fig. 3



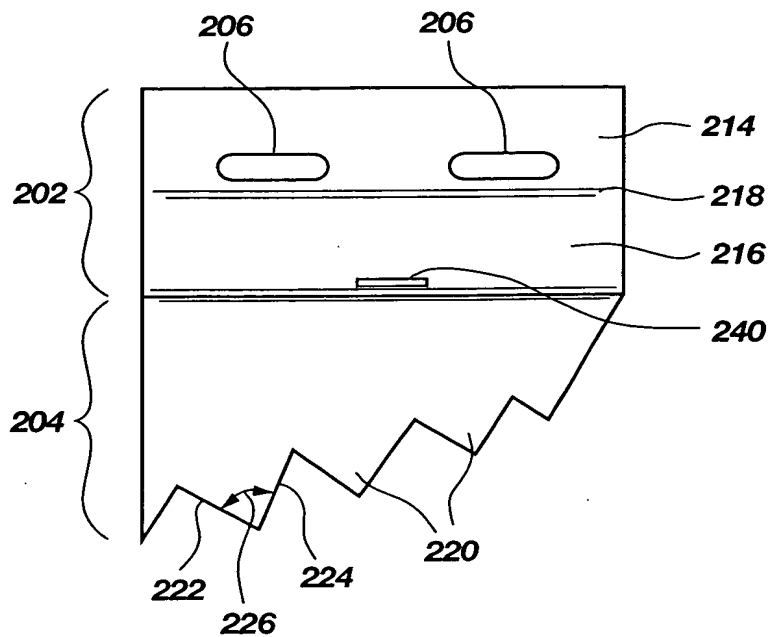
**Fig. 4**



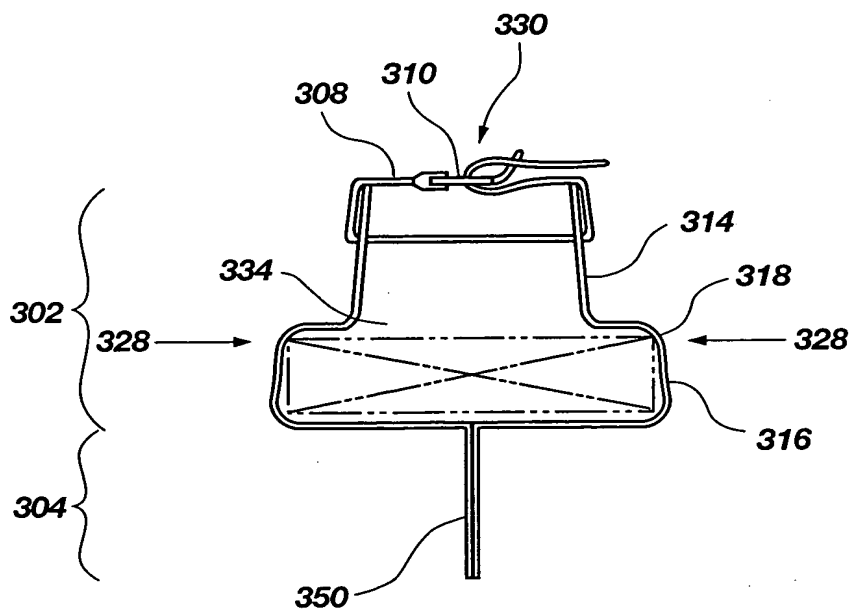
**Fig. 5**



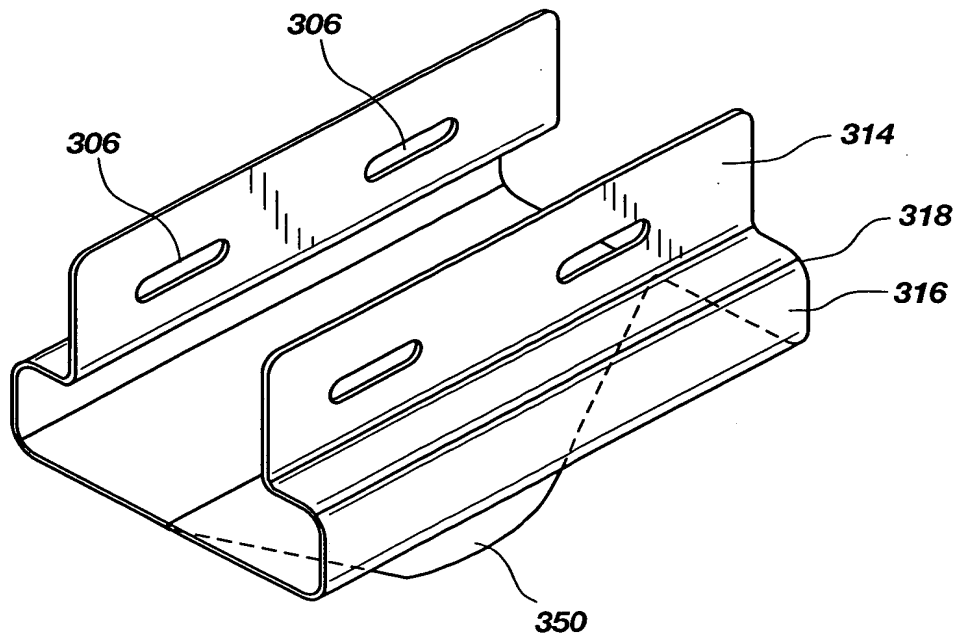
**Fig. 6**



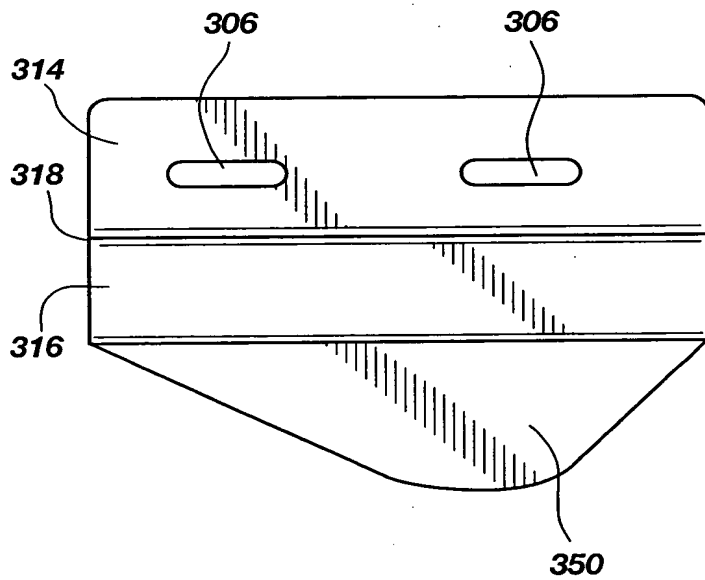
**Fig. 7**



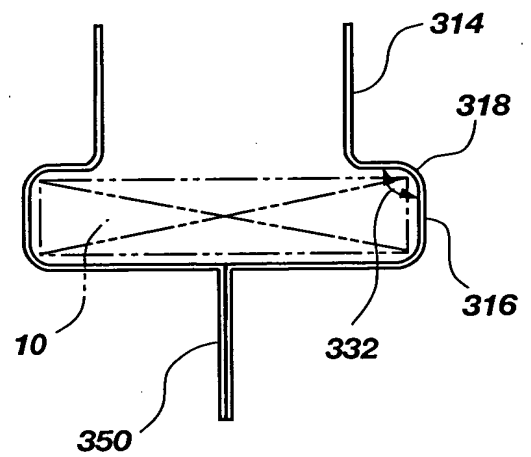
**Fig. 8**



**Fig. 9**



**Fig. 10**



**Fig. 11**

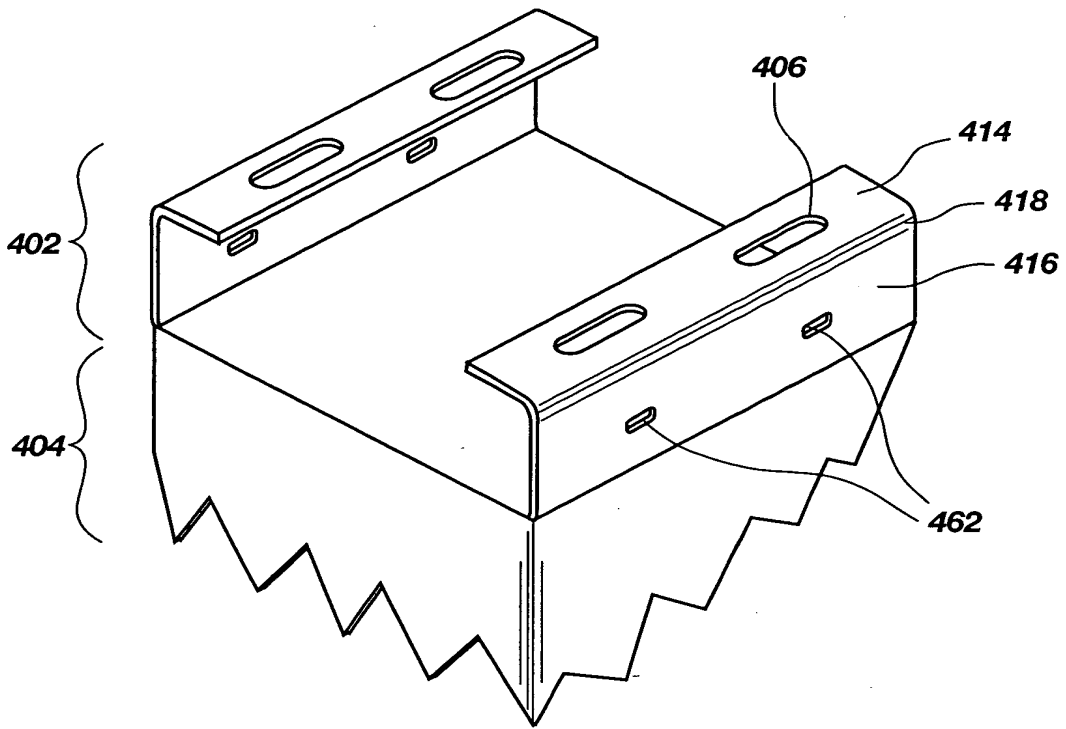


Fig. 12

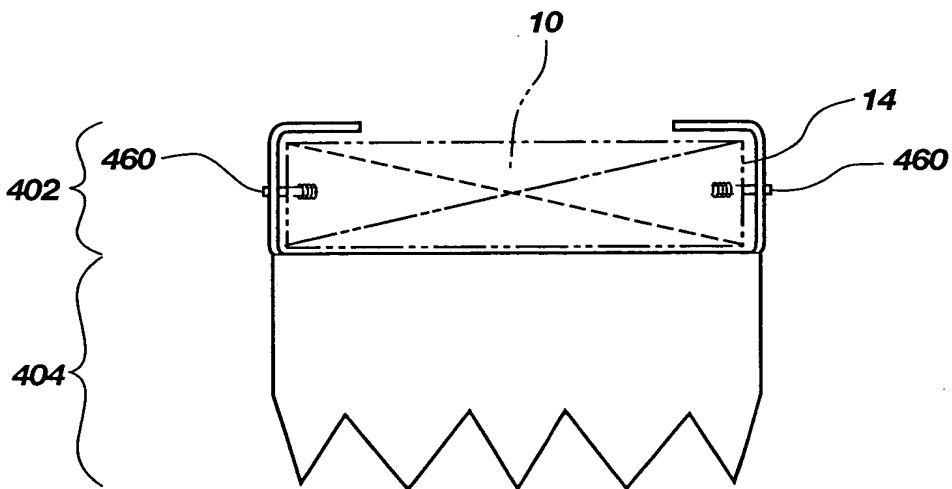
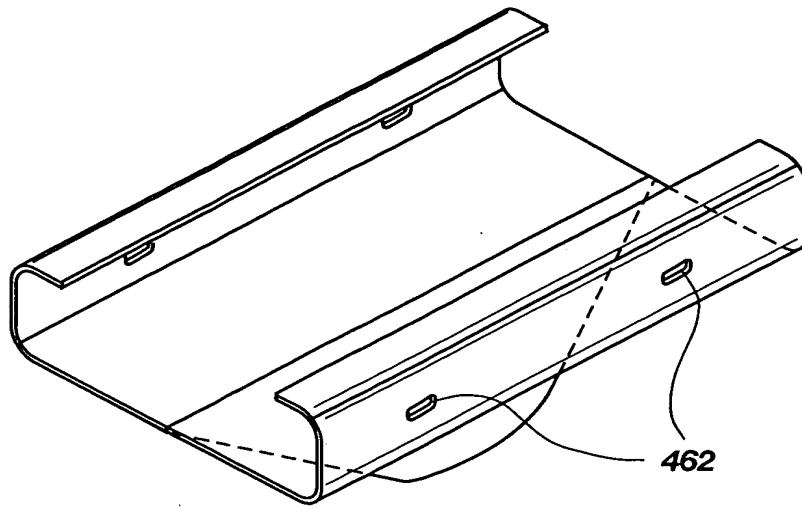


Fig. 12A



**Fig. 13**

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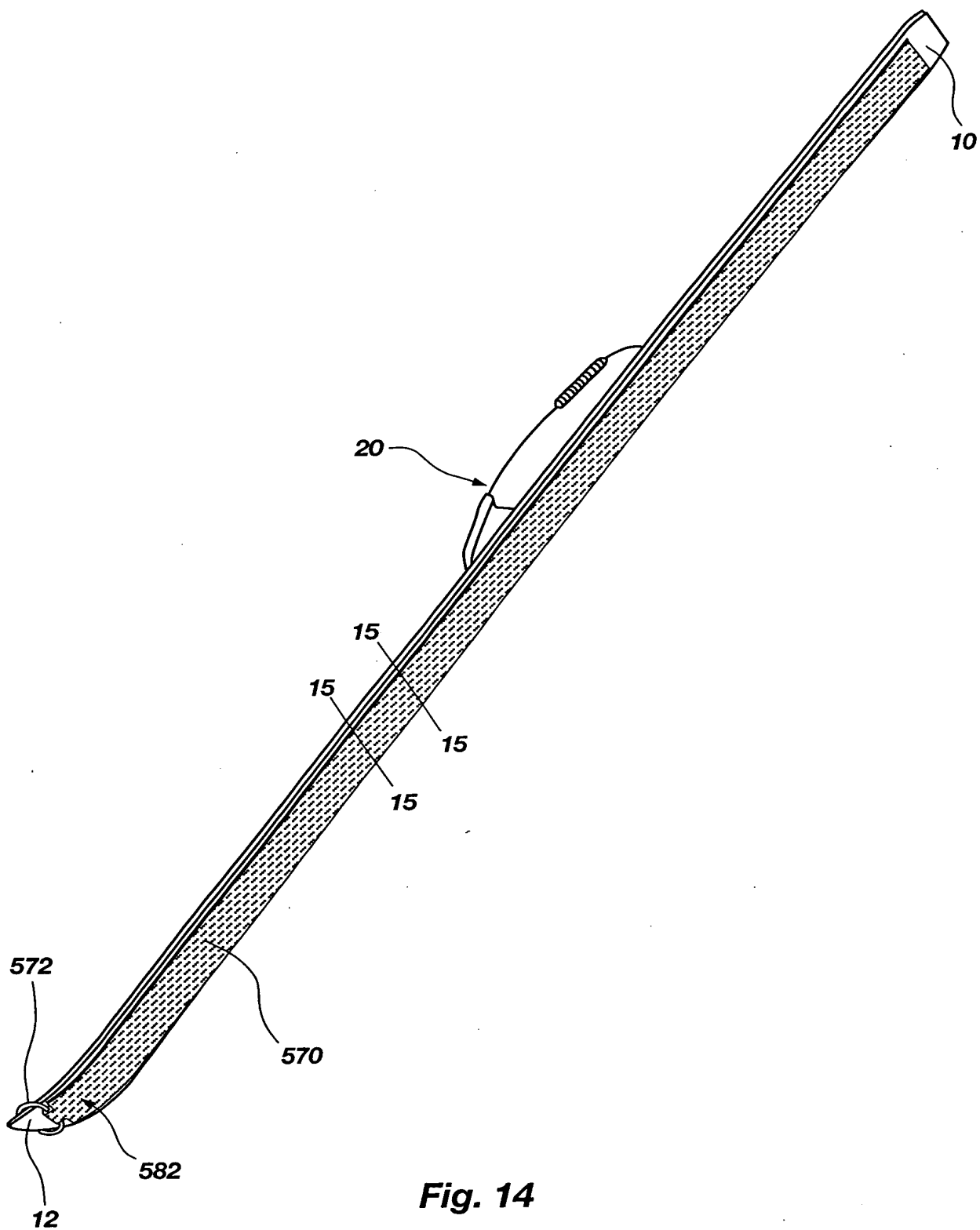
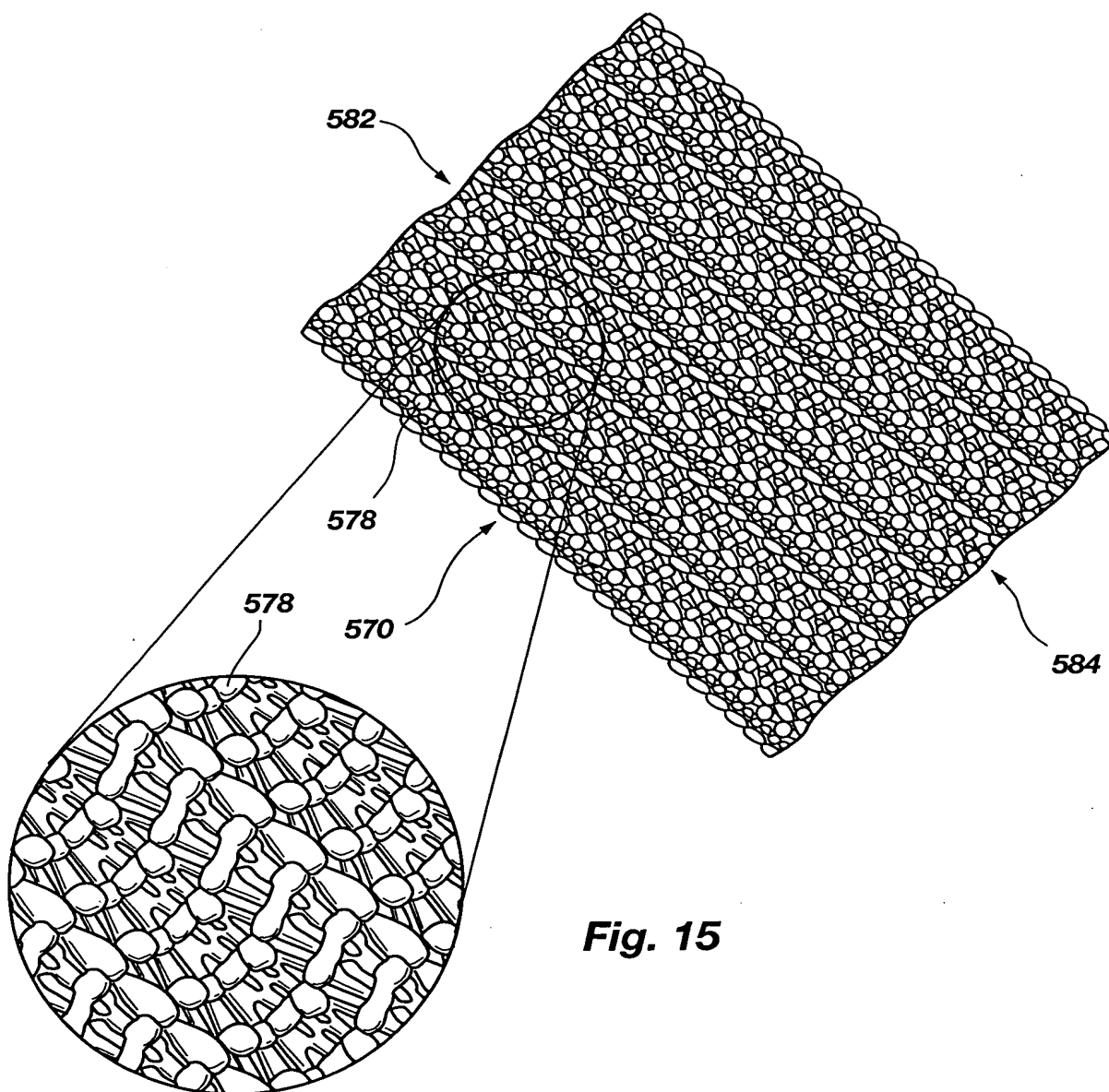
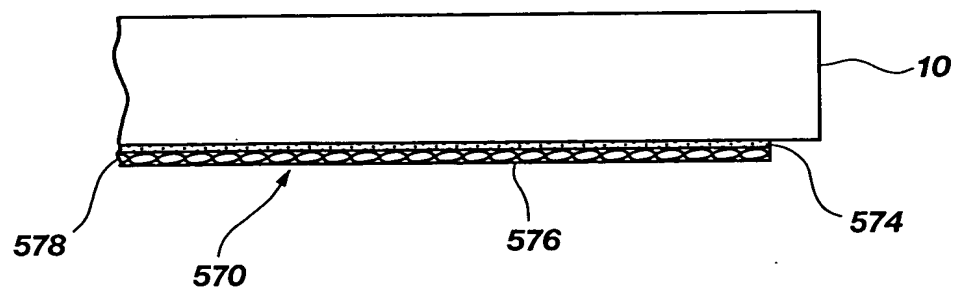


Fig. 14





**Fig. 15**



**Fig. 16**

FIG. 5 is a perspective view of a coil of the tape assembly 574. The assembly includes a substrate 586, a conductive layer 590, and a conductive paste 592. The conductive paste 592 is applied to the conductive layer 590 in a pattern that forms a spiral around the coil.

**Fig. 17**

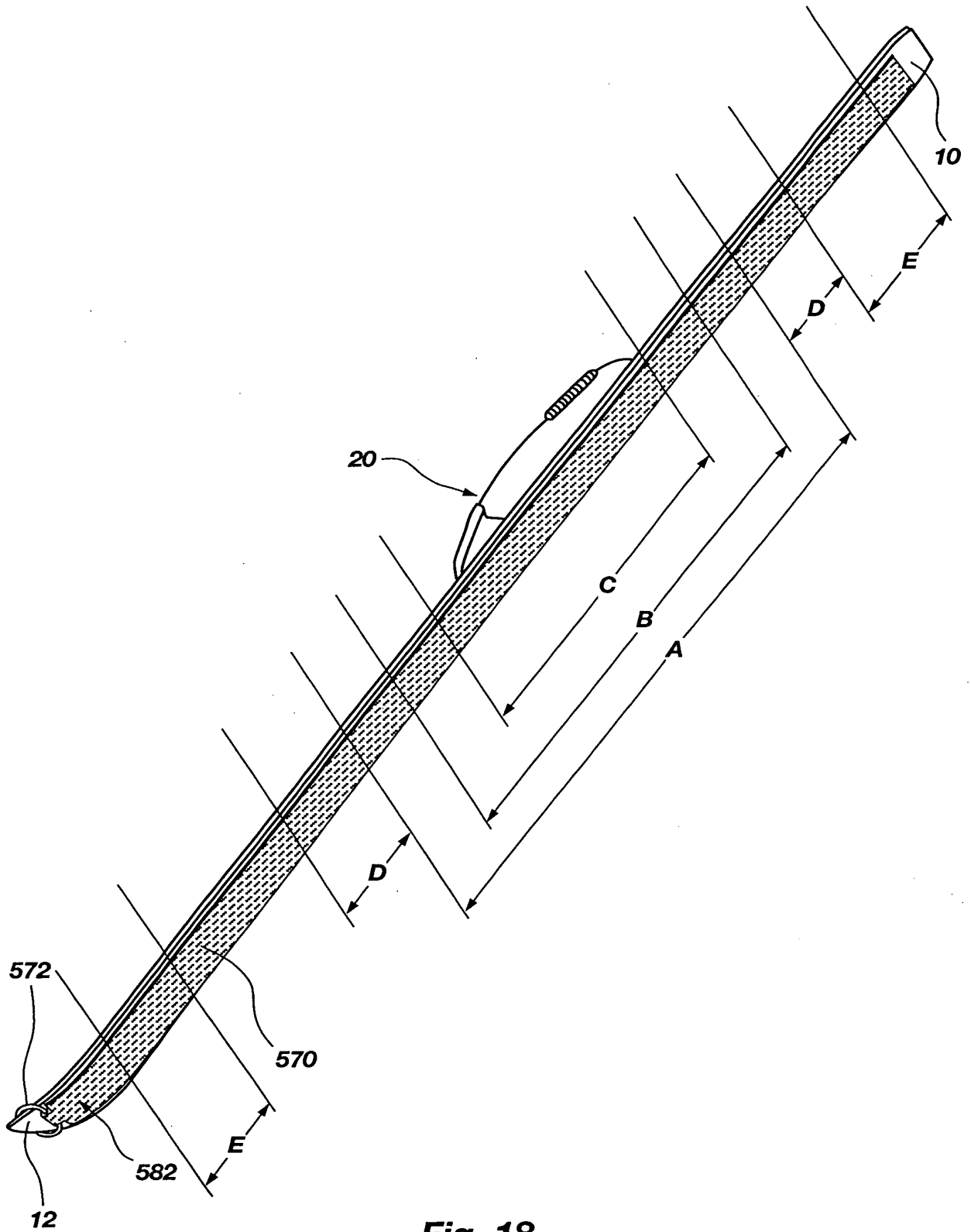
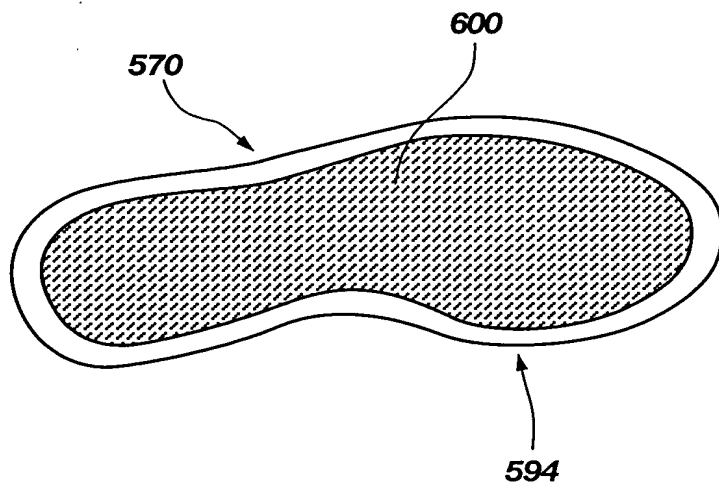
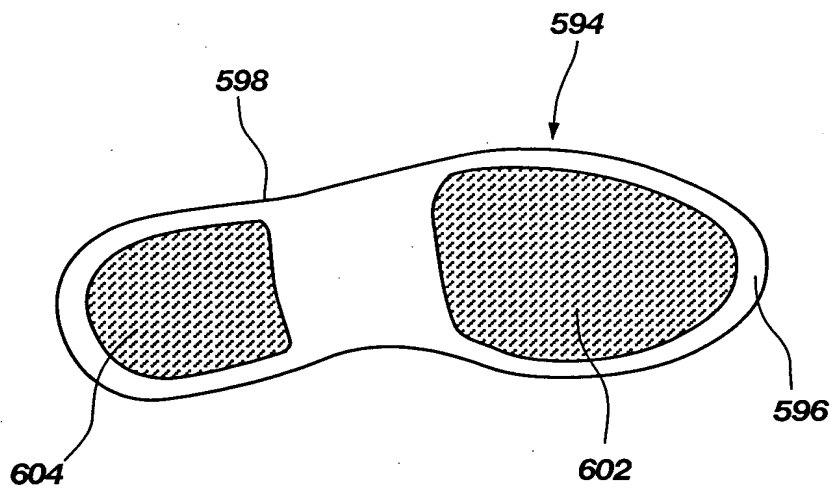


Fig. 18

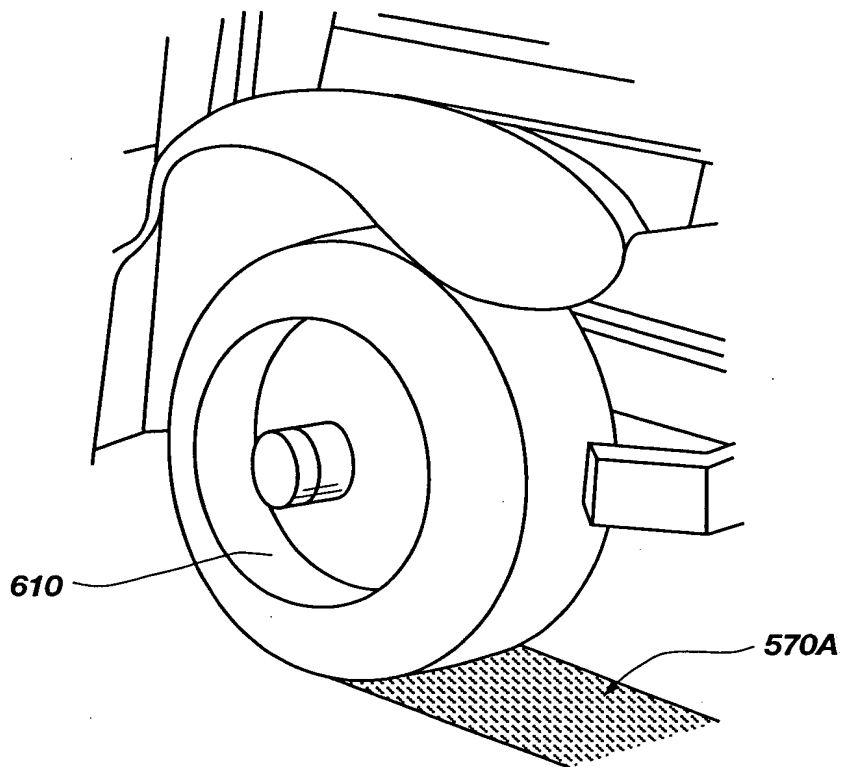
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104207 E1885560



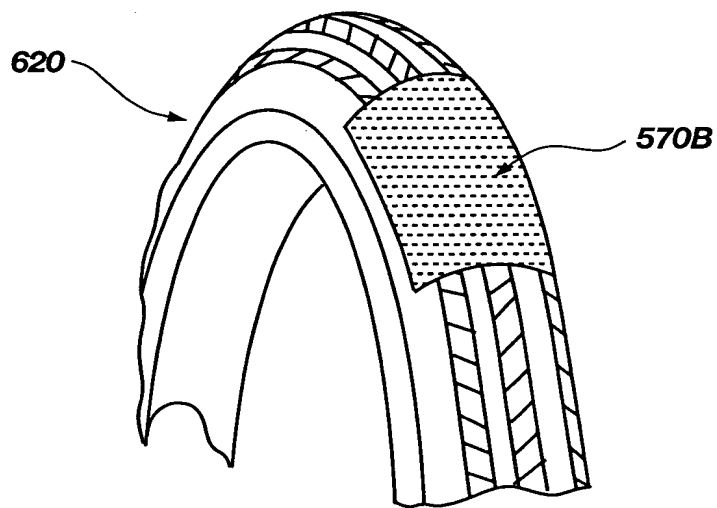
**Fig. 19**



**Fig. 19A**



**Fig. 20**



**Fig. 21**